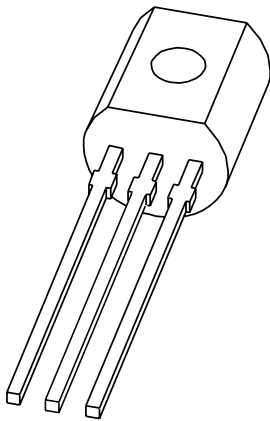


DATA SHEET



BC556; BC557 PNP general purpose transistors

Product data sheet
Supersedes data of 1999 Apr 15

2004 Oct 11

PNP general purpose transistors

BC556; BC557

FEATURES

- x Low current (max. 100 mA)
- x Low voltage (max. 65 V).

APPLICATIONS

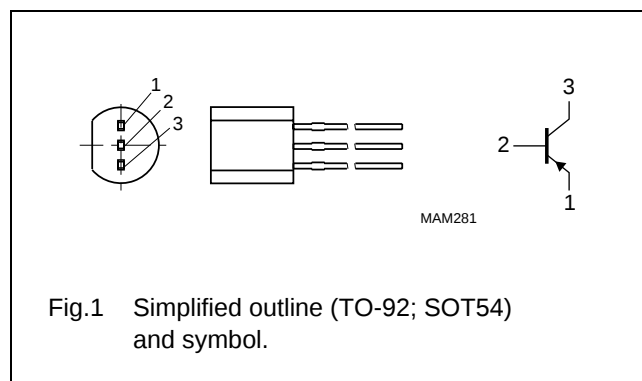
- x General purpose switching and amplification.

DESCRIPTION

PNP transistor in a TO-92; SOT54 plastic package.
NPN complements: BC546 and BC547.

PINNING

PIN	DESCRIPTION
1	emitter
2	base
3	collector



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BC556	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
BC557			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter		80	V
	BC556			50	V
	BC557				
V_{CEO}	collector-emitter voltage	open base		65	V
	BC556			45	V
	BC557				
V_{EBO}	emitter-base voltage	open collector		5	V
I_C	collector current (DC)			100	mA
I_{CM}	peak collector current			200	mA
I_{BM}	peak base current			200	mA
P_{tot}	total power dissipation	T_{amb} d25 $\varnothing$		500	mW
T_{stg}	storage temperature		65	+150	$\varnothing$
T_j	junction temperature			150	$\varnothing$
T_{amb}	ambient temperature		65	+150	$\varnothing$

PNP general purpose transistors

BC556; BC557

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	250	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

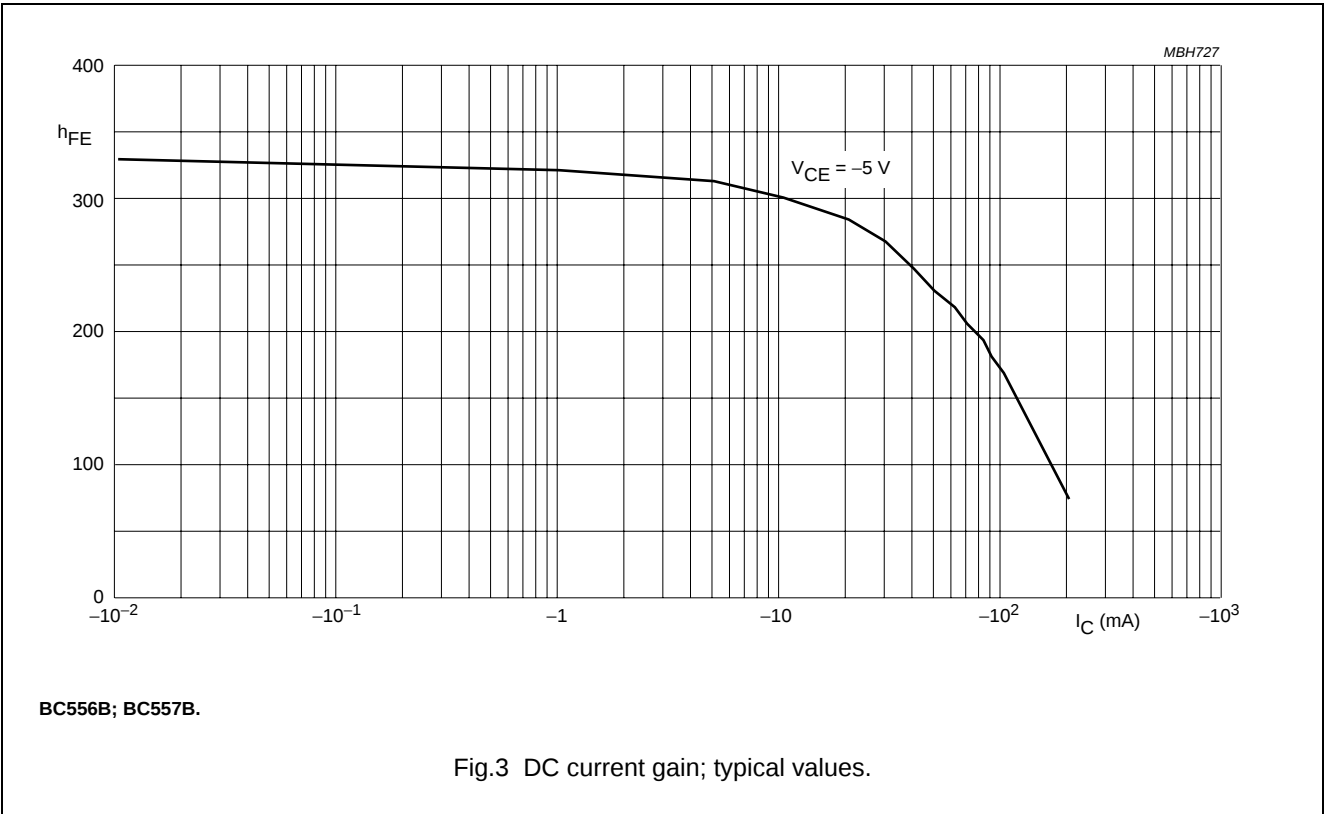
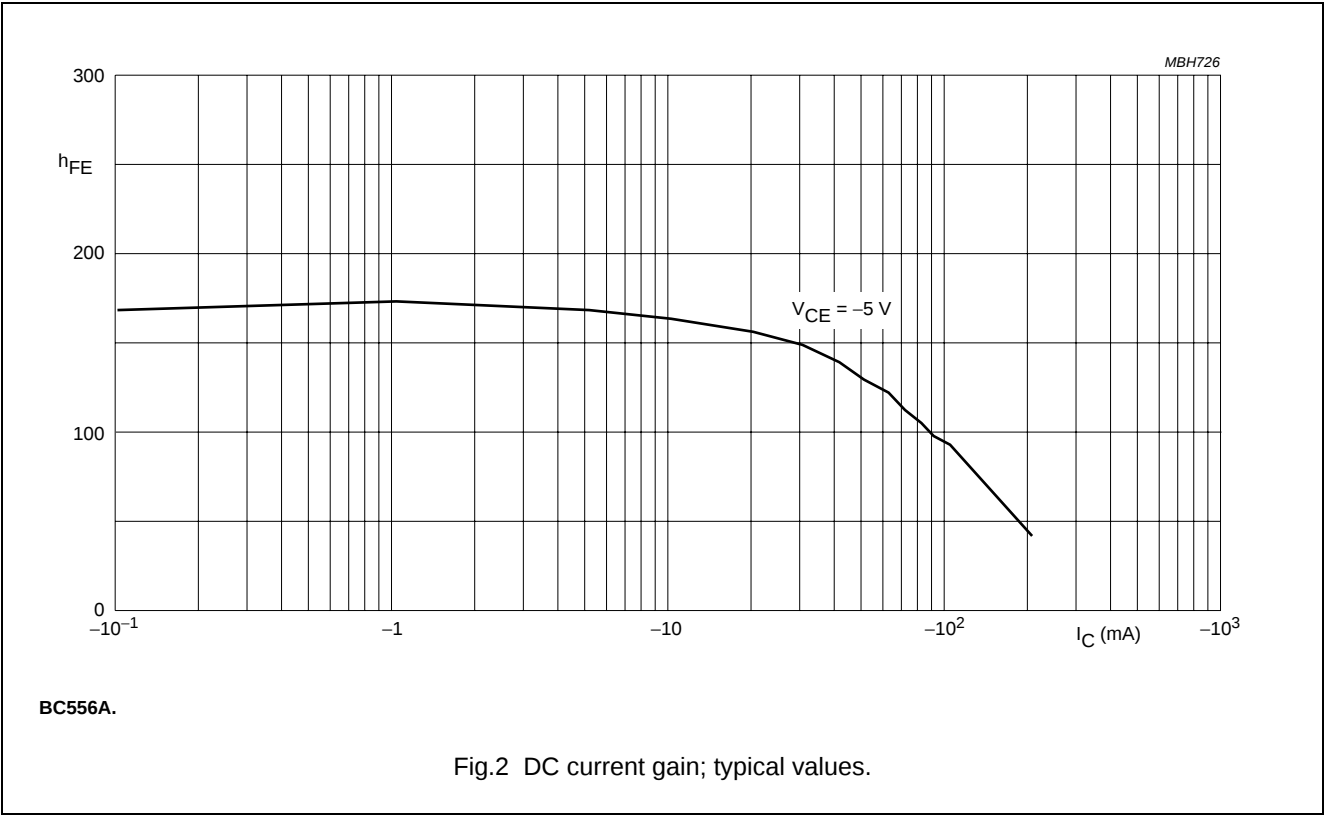
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	$V_{CB} = -30\text{ V}; I_E = 0\text{ A}$	–	–1	–15	nA
		$V_{CB} = -30\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$	–	–	–4	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -5\text{ V}; I_C = 0\text{ V}$	–	–	–100	nA
h_{FE}	DC current gain	$I_C = -2\text{ mA}; V_{CE} = -5\text{ V};$ see Figs 2, 3 and 4	125	–	475	
	BC556					
	BC557					
	BC556A					
	BC556B; BC557B					
	BC557C					
V_{CEsat}	collector-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.5\text{ mA}$	–	–60	–300	mV
		$I_C = -100\text{ mA}; I_B = -5\text{ mA}$	–	–180	–650	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.5\text{ mA};$ note 1	–	–750	–	mV
		$I_C = -100\text{ mA}; I_B = -5\text{ mA};$ note 1	–	–930	–	mV
V_{BE}	base-emitter voltage	$V_{CE} = -5\text{ V}; I_C = -2\text{ mA};$ note 2	–600	–650	–750	mV
		$V_{CE} = -5\text{ V}; I_C = -10\text{ mA};$ note 2	–	–	–820	mV
C_c	collector capacitance	$V_{CB} = -10\text{ V}; I_E = I_C = 0\text{ A}; f = 1\text{ MHz}$	–	3	–	pF
C_e	emitter capacitance	$V_{EB} = -0.5\text{ V}; I_C = I_E = 0\text{ A}; f = 1\text{ MHz}$	–	10	–	pF
f_T	transition frequency	$V_{CE} = -5\text{ V}; I_C = -10\text{ mA}; f = 100\text{ MHz}$	100	–	–	MHz
F	noise figure	$V_{CE} = -5\text{ V}; I_C = -200\text{ }\mu\text{A}; R_S = 2\text{ k}\Omega;$ $f = 1\text{ kHz}; B = 200\text{ Hz}$	–	2	10	dB

Notes

1. V_{BEsat} decreases by about -1.7 mV/K with increasing temperature.
2. V_{BE} decreases by about -2 mV/K with increasing temperature.

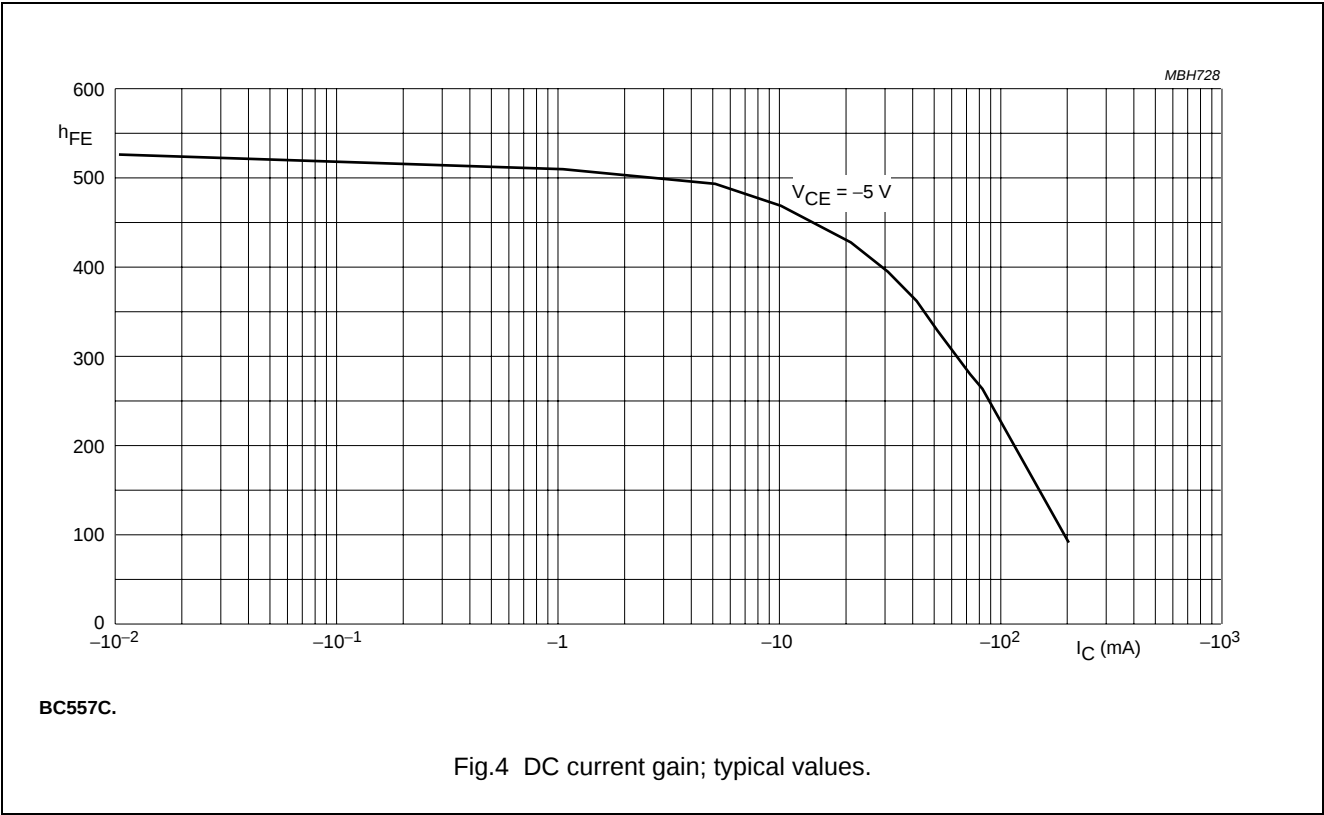
PNP general purpose transistors

BC556; BC557



PNP general purpose transistors

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PNP general purpose transistors

BC556; BC557

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads

SOT54

The diagram illustrates the mechanical specifications of the SOT54 package. It includes three views: a top view showing the circular body with three leads, a side view showing the profile of the package and leads, and an end view showing the lead spacing. Dimensions are labeled as follows: A (body length), b (lead thickness), b₁ (lead width), c (lead thickness at tip), D (body diameter), d (lead diameter), E (body width), e (lead height), e₁ (lead height at base), L (lead length), and L₁ (lead length from body). A scale bar indicates 0, 2.5, and 5 mm.

DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b ₁	c	D	d	E	e	e ₁	L	L ₁ ⁽¹⁾ max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			04-06-28 04-11-16

PNP general purpose transistors

BC556; BC557

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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